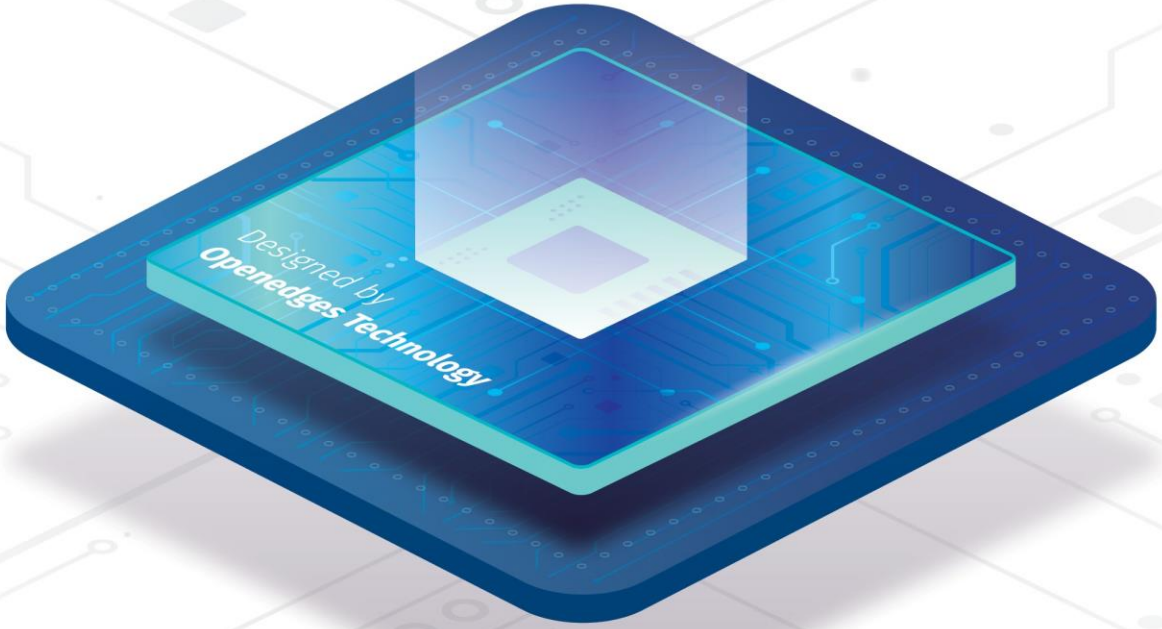
AI for Everyone, Everywhere



INVESTOR RELATIONS 2023

OPENEDGES
Technology, Inc.

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OPENEDGES
Technology, Inc.

The Future of AI Computing

Table of Contents

Openedges Technology at a Glance

98%

Sales Revenue CAGR(Last 5yrs)

* FY2019~2023

52

Number of Cumulative License Agreements

* As of 2023.12.31

130

Global R&D Engineers

* Largest among Korean IP Providers

AI for Everyone, Everywhere

OPENEDGES Technology, Inc.

30+

Number of Clients

* Secured global top-tier customers such as Samsung Electronics, SK Hynix, and Micron

20+

IP products available for sale

* Number of IP Products within 4 IP categories

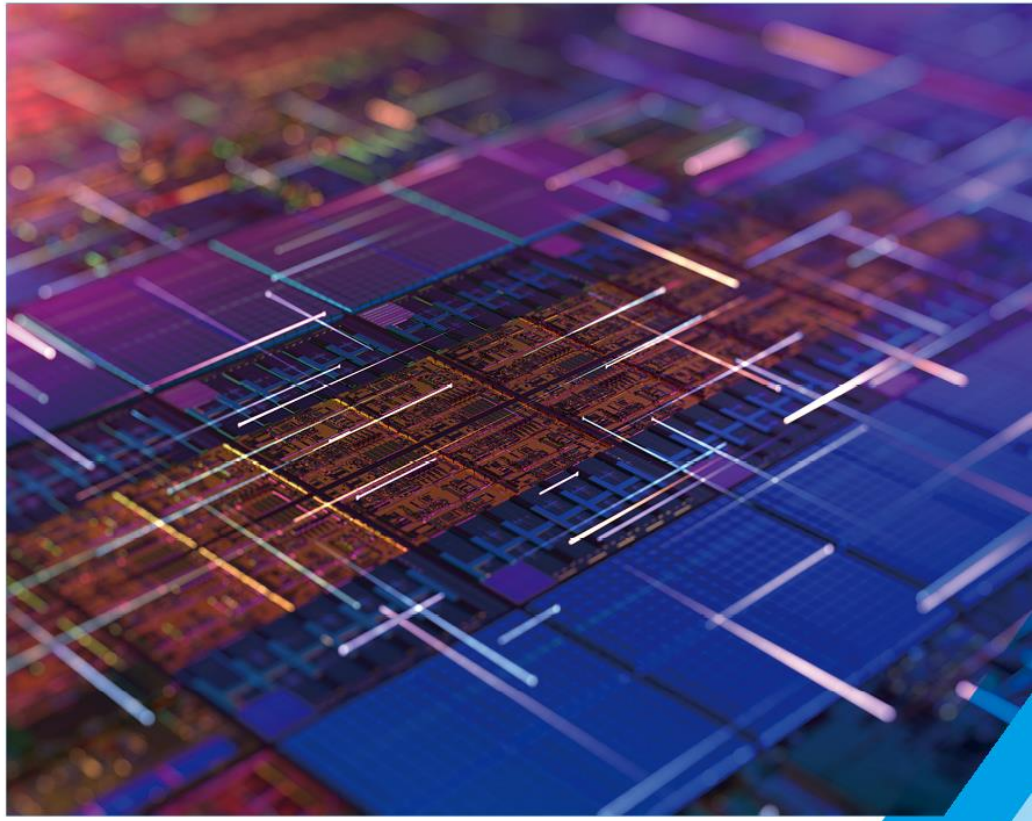
3

Global R&D Centers

* Located in Korea, US & Canada

Prologue

OPENEDGES Technology's Business Areas

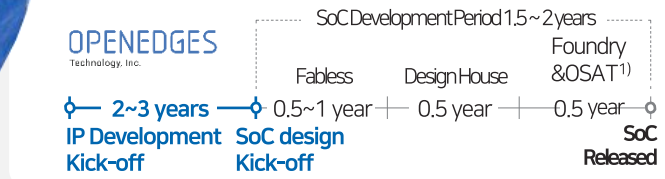


OPENEDGES Technology's Business Areas ①

Semiconductor IP is a ready-made solution requiring high-level technologies that enable faster development of SoC (System on Chip) such as AI semiconductors, reduce costs, and mitigate the risk of failure risks in development that can cost $100 million

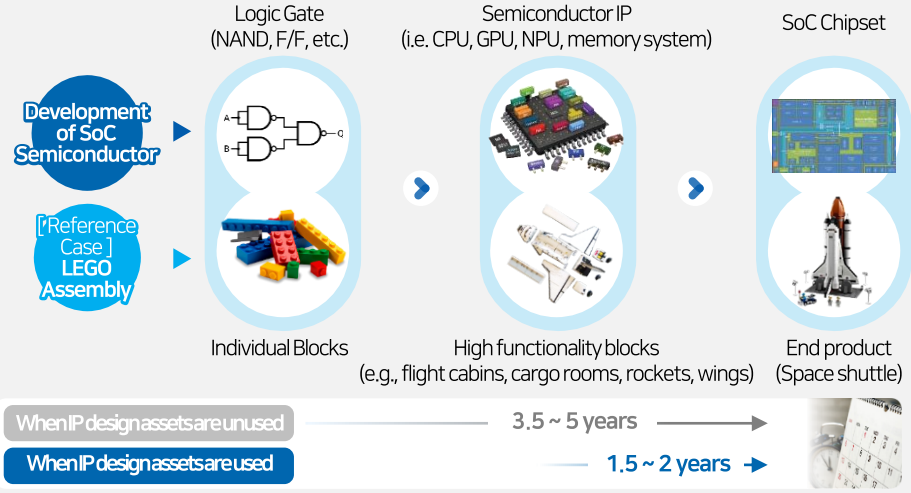
What is Semiconductor IP?

Previously designed/verified function blocks, such as CPU, GPU, and NPU, that can be embedded in SoC

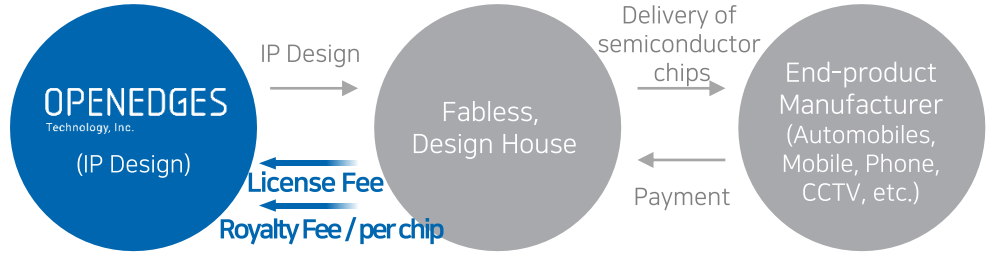


※ Note 1) Outsourced Semiconductor Assembly and Test (Packaging and backend company)

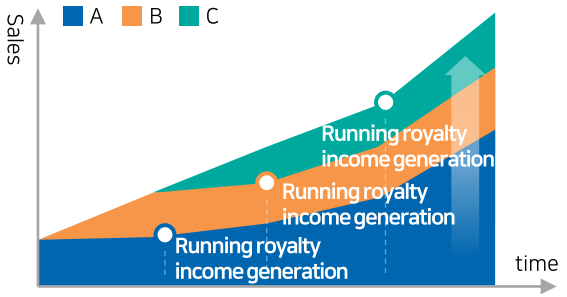
Reduction in SoC design time and cost for fabless companies



Semiconductor IP Business Profit Structure



※ The semiconductor IP industry has been oligopolistic, dominated by a few market players due to high technical barriers to entry.



OPENEDGES Technology's Business Areas ②

Design and provision of integrated IP solution that serves as a basis for AI semiconductor operation

AI Semiconductor

Neural network processing unit optimized for training and inferencing of artificial intelligence

① NPU

Controlling high-speed data communications between SoC and DRAM according to scheduling algorithm

③ Memory Controller

DDR DRAM

④ PHY

High-speed data transfer between SoC and DRAM

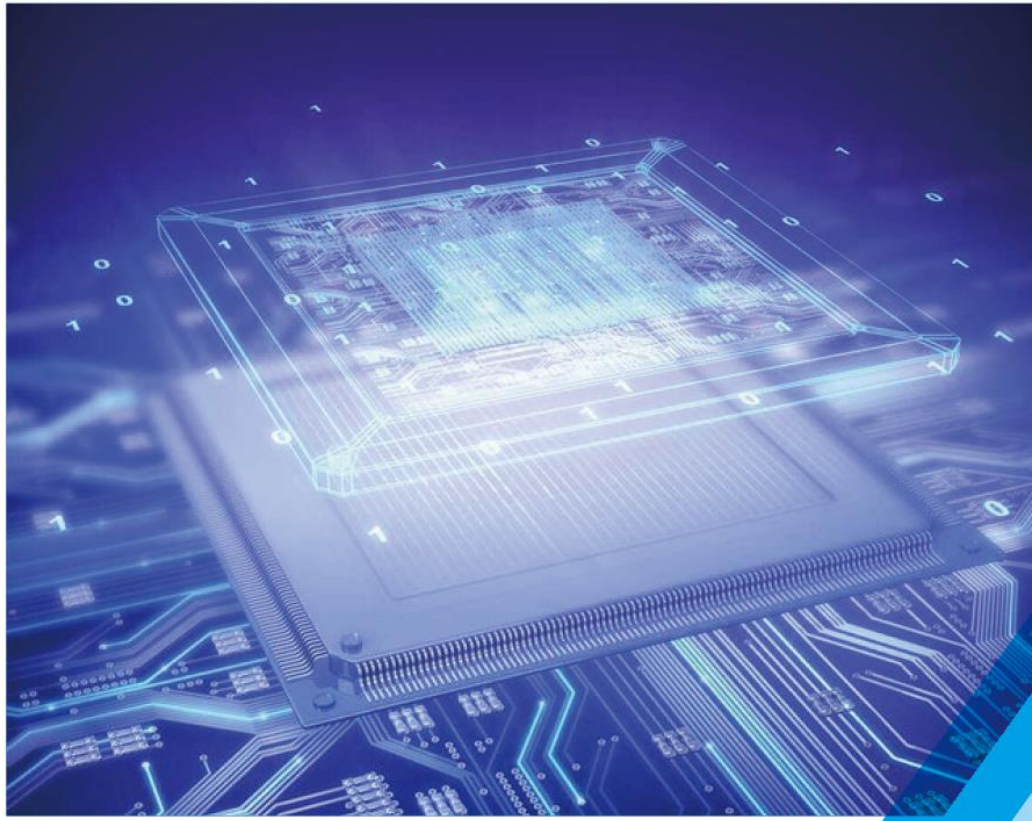
② On Chip Interconnect

Data transfer channel within SoC

01

Structural Development of System Semiconductor Market

01. Growth of AI Semiconductor & IP Market
02. Roles of Semiconductor IP Design Company



01 | Growth of Global System Semiconductor Market

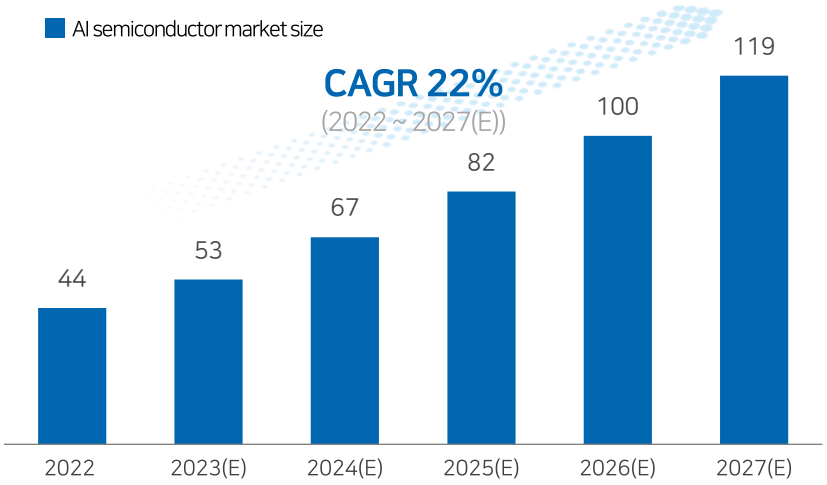
Contrary to memory semiconductors, system semiconductors are continuing their steady growth

Prospects for Global Semiconductor Market 2024

※ Source: WSTS, Nov 2023 (Excluding Optoelectronics, Discrete Semiconductors and sensors)

Prospects of Global AI Semiconductor Market

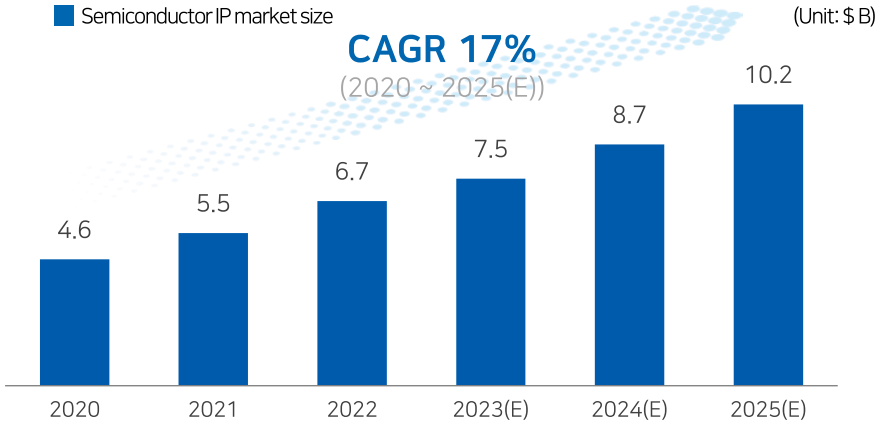
(Unit: $ B)



※ Source: AI Semiconductor (Gartner, Aug 2023), Estimated by company

Global Semiconductor IP market forecast

Company	2022 Sales ($ M)	CAGR (2018-2022)
arm	2,742	14%
SYNOPSYS	1,315	20%
cadence	358	17%
OPENEDGES Technology, Inc.	7.7	95%
Others		14%
Total		16%



※ Source: Design IP revenues (Ipnest, Apr 2023), Press Clipping

03 | Roles of Semiconductor IP Design Companies

Semiconductor IP companies aim to develop and supply function blocks as needed by Fabless and Design House in a proactive manner.

System Semiconductor Ecosystem

	Semicon-ductor IP Design Company	Fabless	Design House	Foundry	OSAT[1)]
Major Role	Design of major semiconductor function blocks	Semiconductor chip design (Frontend design)	Semiconductor chip design outsourced (Backend design)	Semiconductor chip manufacturing (Wafer processing)	Post-processing (packaging)
Number of players	Oligopolistic by ~20 companies	At least 3,000	N/A[2)]	Top 10 M/S 97% M/S	Top 25 M/S 50% M/S
Size	$7B *The highest per-company market share	$170B	N/A	$104B	$50B
Major players	OPENEDGES Technology, Inc., arm, SYNOPSYS, cadence	Qualcomm, NVIDIA, BROADCOM, MEDIATEK, AMD	GUC, GAONCHIPS, ASICLAND	tsmc, SAMSUNG, GLOBAL FOUNDRIES, UMC	ASE GROUP, Amkor Technology, JCET, SPIL

Reasons for IP oligopoly

Higher demand for proven IPs

IP companies with proven IPs are in high demand due to the rising entry barriers

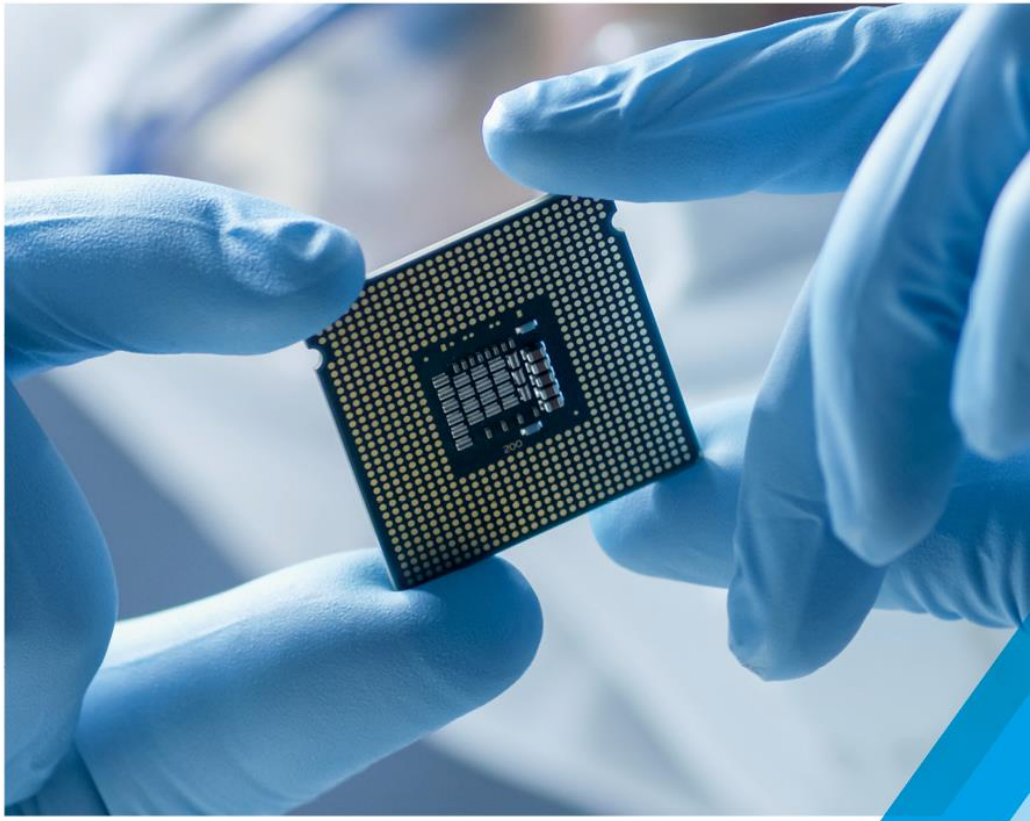
- Requires highly proficient technical personnel
- Requires R&D investments for at least 3 years

※ Note 1) (Outsourced) Semiconductor Assembly and Test: Semiconductor package assembly and test company that is responsible for performing post-processing after wafer process
Note 2) Design House market does not have a reliable market size data as it is in its initial formation stage.

02

OPENEDGES Technology, as Korea's most renowned AI semiconductor IP design company

01. The Overview of OPENEDGES's Core Competitiveness
02. A Global Team of Professionals
03. Industry's Highest Technological Competitiveness
04. Verified Global Track Records
05. Business Partnership with Global Enterprises

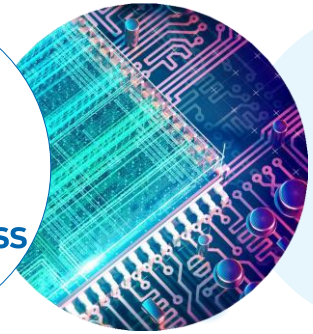


01 | The Overview of OPENEDGES' Core Competitiveness

OPENEDGES holds the key success factors
to become a global leader in the AI semiconductor IP market

01
A Global team of Professionals

02
Industry's highest technological competitiveness



OPENEDGES
Technology, Inc.

03
Verified global track records

04
Strategic partnership with global enterprises

02 | A Global Team of Professionals – Global Presence

OPENEDGES Technology, Inc.

50%

Openedges Square

Major roles: Online IP Sales Platform

Establishment: August 2023

100%

Openedges Square Corporation

Major roles: Cache Coherence NOC IP R&D

Establishment: August 2023

100%

Openedges Technology Corporation

Major roles: Sales hub for North America regions

Establishment: July 2021

100%

The Six Semiconductor

Major roles: DDR PHY IP R&D

Establishment: June 2018 (Acquired in December 2019)

* Operating base in Toronto

* Considering establishment of sales office in Shanghai

* A sales office is in operation (Yokohama), and recruitment of personnel and establishment of a corporation are in progress (March 2024).

* Operating bases in San Jose and Austin

Expansion of global bases in addition to offices in the U.S. and Canada

02 | A Global Team of Professionals

Leadership of industry-leading experts with over 20 years of experience from Samsung Electronics/SK Hynix, and more.

R&D personnel

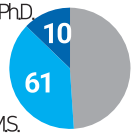
Among the total personnel (152 team members)

86%

130
R&D personnel

Percentage of Ph.D. and M.S. degree holders (71 members) among the R&D personnel

47%



Status of Each Country

Korea HQ (93 members)

U.S.A. (9 members)

Canada (43 members)

Sean Lee
Representative Director / CEO

SAMSUNG | SAMSUNG ADVANCED INSTITUTE OF TECHNOLOGY

Ph.D. Candidate in Electrical and Computer Engineering, Seoul National University
• 2017-Present: Representative Director, OPENEDGES Technology, Inc.
• 2008-2015: Principal Researcher, Samsung Electronics (Exynos Development)
• 2007-2008: Samsung Advanced Institute of Technology

Jake Choi
NPU Team Head

SK hynix | SAMSUNG

Ph.D. in Electrical and Computer Engineering, Purdue University
• 2018-Present: NPU Team Head, OPENEDGES Technology, Inc.
• 2015-2018: Principal Researcher, SK Hynix
• 2009-2014: Architecture Lab Part Head, Samsung Electronics

Richard Fung
TSS / CEO

AMD | PERASO

M.S. in Electrical and Electronic Engineering, Univ. of Toronto
• 2018-Present: CEO, The Six Semiconductor
• 2012-2018: Silicon Director, etc., Peraso Technologies
• 2000-2011: PHY Analog Design Manager, AMD

Moez Cherif

ARTERIS IP | MAGMA | SYNOPSYS

Ph.D. in Computer Science, INPG Univ.
• 2021-Present: S/W Group Head, U.S. entity of OPENEDGES Technology
• 2018-2021: Principal S/W Architect, Arteris IP
• 1995-2017: Synopsys, Magma Design Automation, etc.

Cody Hwang
R&D Center Head / CTO / Co-founder

Codeholics | 대우전자 | Chips&Media

M.S.in Electrical Engineering, Seoul National University
• 2017- Present: CTO, OPENEDGES Technology, Inc.
• 2010-2015: CTO, CodeHolics
• 2000-2010: Daewoo Electronics, Chips & Media

Henry Moon
Memory controller Team Head

SK hynix | SAMSUNG

M.S.in Computer Engineering, Seoul National University
• 2018-Present: MC Team Head, OPENEDGES Technology, Inc.
• 2017-2018: Memory System Laboratory Part Head, SK Hynix
• 2000-2016: AP Development Team Part Head, Samsung Electronics

Ricky Lau
TSS / CTO

AMD | SYNOPSYS

M.S. in Electrical and Electronic Engineering, Univ. of Toronto
• 2018-Present: CTO, The Six Semiconductor
• 2014-2018: PHY Digital Design Engineer, Synopsys
• 2003-2014: PHY Analog Design Engineer, etc., AMD

Roger Jennings
OTC / VP of Engineering

ARTERIS IP | AMD | intel

M.S. in Electrical and Electronic Engineering, Univ. of Memphis
• 2022-Present: VP of Engineering, U.S. entity of OPENEDGES Technology, Inc.
• 2020-2022: Arteris IP Senior Director of Engineering
• 2000-2021: Intel, Juniper Networks, AMD etc.

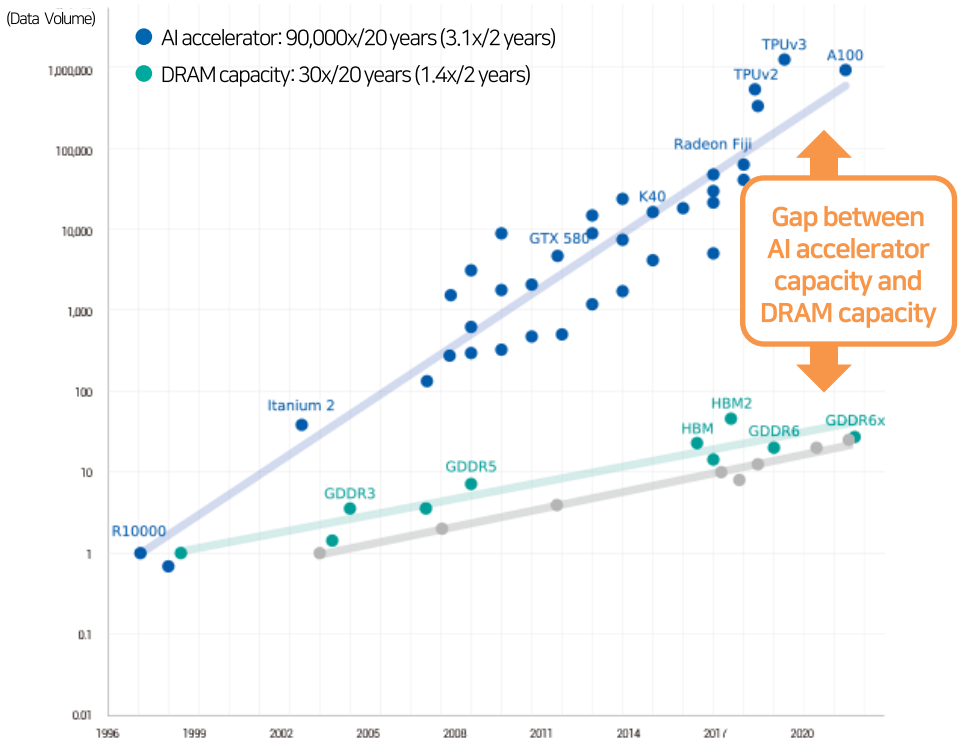
※ As of the end of Dec. 2023

03 | Industry's Highest Technological Competitiveness ①

AI semiconductors are characterized as 'Data Intensive Computing'
→ Most optimize NPU and memory systems in edge AI with limited resources

OPENEDGES is the only global leading AI semiconductor IP platform provider

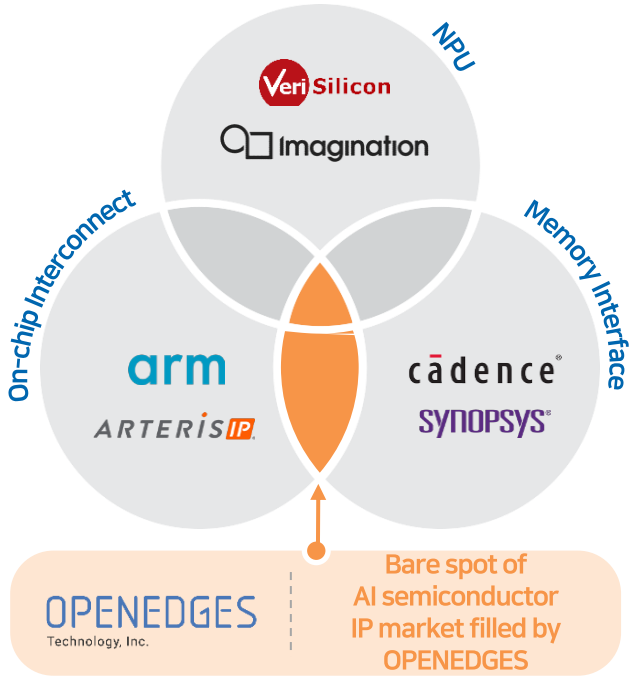
The gap between the required data processing volume and the capacity provided by DRAMs has increased due to the development of AI accelerator technologies



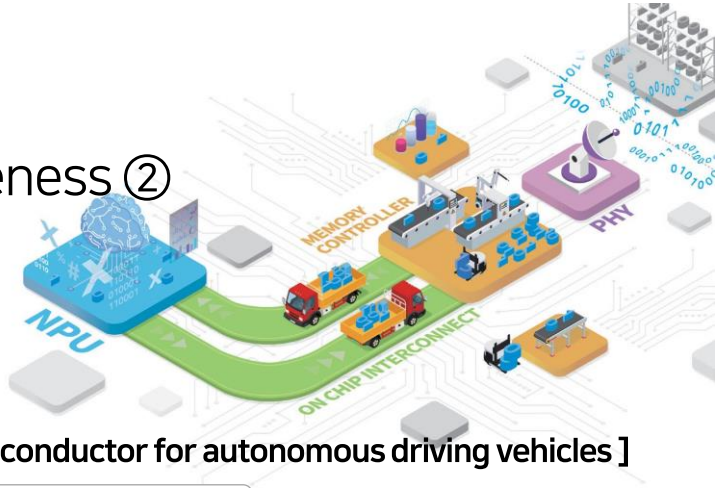
※ Source: AI And Memory Wall By Riselab

AI Platform IP for Edge Computing

OPENEDGES is globally the only company that is capable of supplying NPU IP (the core of AI semiconductors) and memory system IP (functions as the 'Back Bone' for all semiconductors) at the same time.



03 | Industry's Highest Technological Competitiveness ②

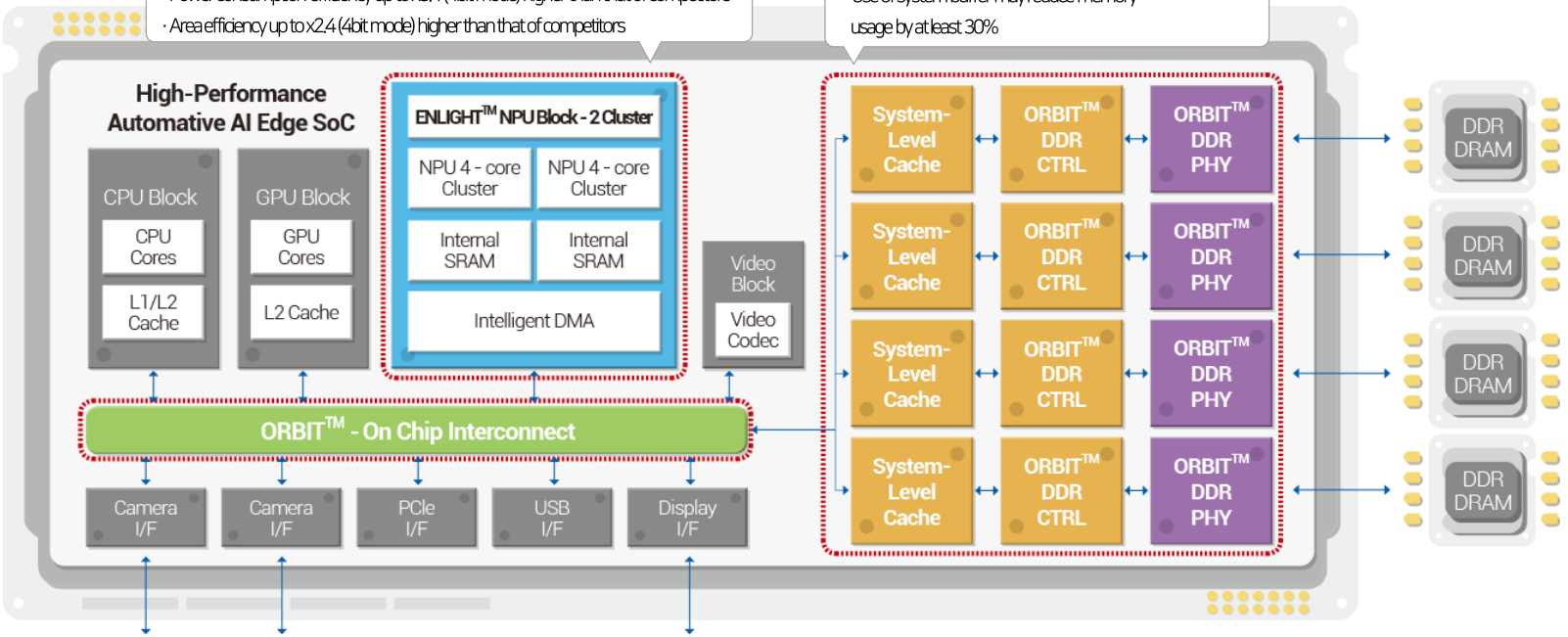


A leading AI semiconductor IP platform provider, OPENEDGES provides higher efficiencies in power, size, and memory compared to its competitors

[Examples showing OPENEDGES' integrated IP solutions applied to the AI semiconductor for autonomous driving vehicles]

Openedges ENLIGHT™ NPU
- Power consumption efficiency up to x3.4 (4bit mode) higher than that of competitors
- Area efficiency up to x2.4 (4bit mode) higher than that of competitors

Openedges ORBIT™ Memory System
- Use of system buffer may reduce memory usage by at least 30%



OPENEDGES Technology, Inc.

03 | Industry's Highest Technological Competitiveness ③

Leading the market through the development of cutting-edge technology

구분	IP	Description	개발현황	Remark
AI Platform IP Solution for Edge Computing	ENLIGHT™ (Neural Processing Unit)	ENLIGHT™-L(1st gen. a.k.a v1.0)	Now	Lightweight IoT applications (Keyword recognition, security camera application)
		ENLIGHT™-R(2nd gen. a.k.a v2.0)	Now	Intermediate IoT applications (ADAS)
		ENLIGHT™-P(3rd gen. a.k.a v3.0)	**In the process ('24 1H release)**	**Automotive high-performance applications (Level 3 or higher self-driving vehicle application)**
		ENLIGHT™-X(4th gen. a.k.a v4.0)	In the future	Automotive high-performance applications (Level 4 or higher self-driving vehicle application)
Total Memory System Solution IP (ORBIT™)	OMC™ (DDR Memory Controller)	DDR4/3, LPDDR4X/4/3	Now	Current Mainstream Technology
		LPDDR5X/5/4X/4	Now	Next-generation Mainstream Technology
		HBM3	Now	Server and ultra-high-performance products
		DDR5	Now	Next-generation Mainstream Technology
		GDDR6	Now	High-performance AI product
		GDDR7	In the future	High-performance AI product
		LPDDR6	**Near future('24)**	**Next-generation Mainstream Technology**
	OPHY™ (DDR PHY)	LPDDR4X/4	Now	TSMC 22nm Nodes
		LPDDR5/4X/4	Now	TSMC 16nm Nodes
		LPDDR4X/4, LPDDR5/4X/4	Now	TSMC 12nm Nodes
		GDDR6	Now	TSMC 12nm Nodes
		LPDDR5X/5/4X/4	Now	TSMC 6/7nm Nodes
		HBM3	Now	TSMC 6/7nm Nodes
		DDR5	**Near future('24)**	**TSMC 5nm Nodes**
		LPDDR6	In the future	TSMC 4nm(or less) Nodes
		LPDDR3, DDR4/3	Now	Samsung 28nm Nodes
		LPDDR4X/4, LPDDR5/4X/4	Now	Samsung 14nm Nodes
		LPDDR5/4X/4	Now	Samsung 8nm Nodes
		LPDDR5X/5/4X/4	Now	Samsung 5nm Nodes
		LPDDR6	**Near future('24)**	**Samsung 4nm(or less) Nodes**
		GDDR7	In the future	-
	OIC™ (On-Chip-Interconnect)	OIC™	**Now (v2 released in '24)**	Non-Cache-Coherent NoC
		OIC™-AI	**In the process**	Cache-Coherent NoC

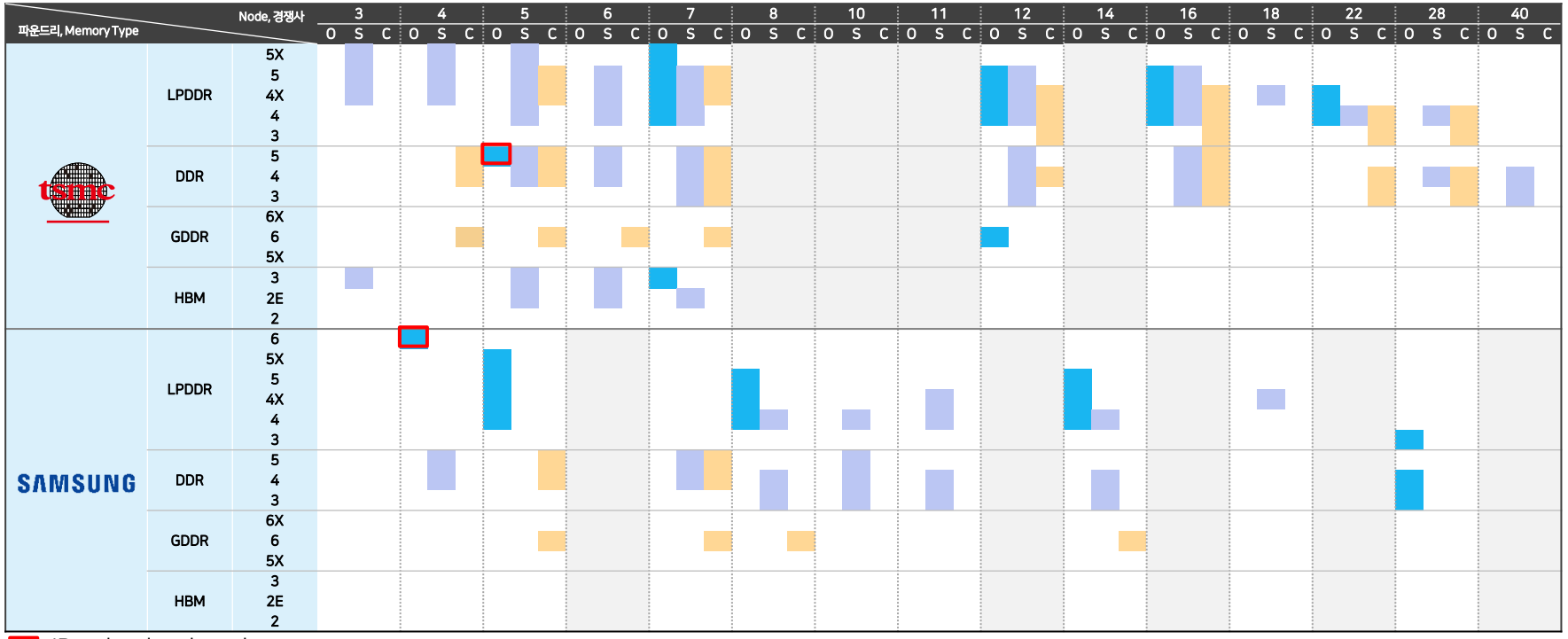
OPENEDGES Technology, Inc.

03 | Industry's Highest Technological Competitiveness ④

Concentrate on areas that major global competitors cannot cover & expand M/S

DDR PHY IP Competition status

Openedges | Synopsys | Cadence



IP to be developed

M/S expansion strategy

- ✓ Synopsys and Cadence are focusing on TSMC 5nm and below leading-edge processes
- ✓ OE is the only one who provides LPDDR5X/5 PHY IP for supporting the SSF 5nm process
- ✓ OE is expecting customer pool through the development of PHY IP for SF 4nm & TSMC 5nm processes
- ✓ OE's PHY IP requires area less than 50% compared to competitors by provding through the test chips

03 | Industry's Highest Technological Competitiveness ⑤

Maximize first-mover advantage of AI semiconductor integrated IP solutions

예상 출시 일정		2021		2022		2023		2024		2025	
		1H	2H	1H	2H	1H	2H	1H	2H	1H	2H
ENLIGHT™ Neural Processing Unit		NPU v1.0		NPU v2.0				NPU v3.0 Autonomous Driving		NPU4.0 Autonomous Driving	
		[Performance] 0.25~2 TOPS / [TargetProduct] Light-weight IoT application products (keyword recognition, security camera application)		[Performance] 2~16 TOPS / [TargetProduct] Medium or higher level of IoT application products (autonomous driving auxiliary application)		[Performance] 16~250 TOPS / [TargetProduct] High-performance application products for vehicles (Application of autonomous driving vehicles with Level 3 or higher)		[Performance] 250~1,000 TOPS / [TargetProduct] High-performance application products for vehicles (Multi-Die version application of autonomous driving vehicles with Level 4 or higher)			
		Security Camera		Driver Support System such as E-Mirror				Self-Driving		Fully Autonomous Driving	
OIC™ On-Chip Interconnect	Non-Cache Coherent NOC	OIC v.1.X						OIC v.2.0			
	Cache Coherent NOC										OIC-AI
OMC™ Memory Controller		GDDR6	LP5X/5/4X/4		HBM3	DDR5				LP6	
OPHY™ DDR PHY	SAMSUNG		LP4/4X/5 (14nm)				LP5X/5/4X (5nm)			LP6 (4nm)	
	tsmc			LP4/4X/5 GDDR6 (12nm)	LP4/4X/5 (22nm)	HBM3 LP4X/5/5X (7nm)				DDR5 (5nm)	
OUC(TBD) Controller Die to Die (Chiplet)									UCIe v1.1 Controller AXI streaming		UCIe v1.1 Controller (Full spec.)
OPHY™ PHY Die to Die (Chiplet)	SAMSUNG										OPHY-D2D (5/8nm)
	tsmc										OPHY-D2D (6nm)

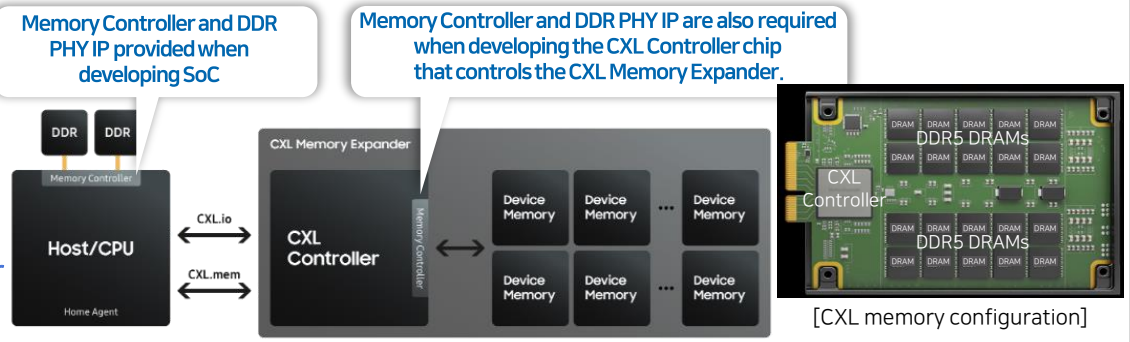
○ R&D started in 2023 ○ R&D to be launched from 2024

03 | Industry's Highest Technological Competitiveness ⑥

Leading the next generation of high value-added semiconductor technology expected to grow rapidly

CXL (Compute eXpress Link)

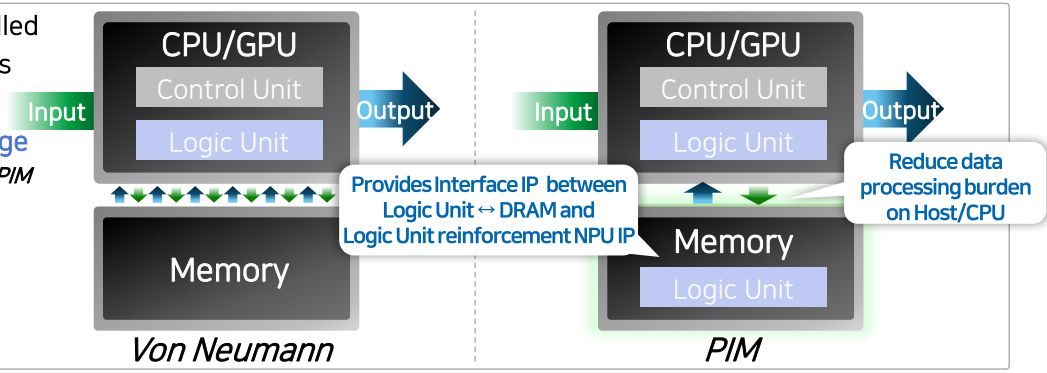
- CXL interface can flexibly expand memory without limitations on memory standard capacity and performance dependent on existing Host/CPU
  → Effectively supports data intensive high-performance calculations such as AI chips
- supplies IP for the design of the CXL Controller chip, the core of the CXL Memory Expander.



[CXL memory configuration]

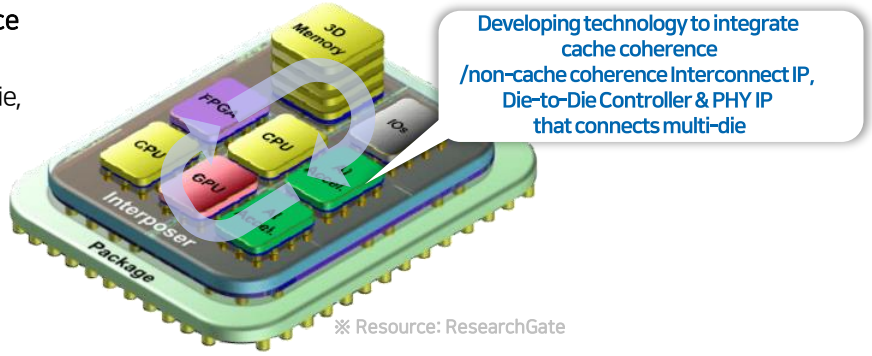
PIM (Process-in-Memory)

- PIM off-loads some of the computational functions handled by the Host/CPU (von Neumann structure) and processes them in the PIM.
  → Speed ↑ , Power ↓ by simultaneous calculation & storage
  ※ Samsung is using HBM and SK Hynix is using GDDR6 for developing PIM
- Supplies Memory System IP, which is responsible for the data interface between Logic Unit and DRAM in PIM semiconductors, and NPU IP required to improve the performance of Logic Unit.



Chiplet

- A chiplet is a SoC that is manufactured by dividing high-performance SoC functions into multiple dies and then packaging them.
  → SoC development cost & Risk ↓ : Optimal process selection for each die, net die increase by reducing chip area
  → Development period ↓ : Independent design for each die, use of previously verified chiplets possible
- provides 'On-chip & Chip-to-Chip Interconnect IP Solution' that can implement multi-die interconnect technology beyond single-die standard interconnect IP.

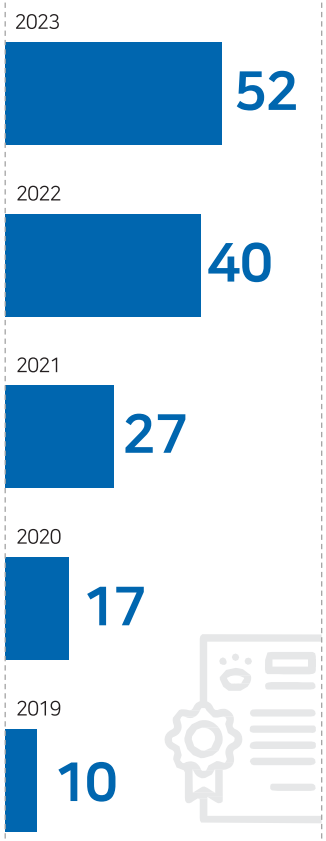


※ Resource: ResearchGate

04 | Verified Global Track Records

Expanding global track record as value recognized as the essential solution in various industries

Number of licenses accumulated each year



05 | Business Partnership with Global Enterprises

Securing stable IP demands + Proactive response to advanced technologies and market trends

Strengthening partnerships with IP companies

Company A
Company C
Company M

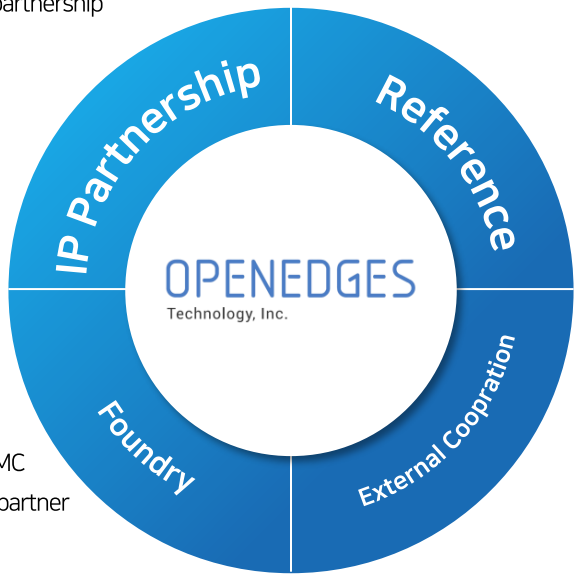
- Under negotiating strategic partnership for providing integrated IP

Qualitas SEMICONDUCTOR
HANA MICRON

- Chiplet government task

Securing references with top-tier customers

SAMSUNG
SK hynix
Micron
Company I
AISIN
alchip
MONTAGE Technology
JLQ TECHNOLOGY



Strengthening partnerships with Foundries

tsmc

- 2 clients who licensed OE IPs are preparing mass production at TSMC
- OE is targeting to join as a formal partner in the TSMC IP Alliance Program

SAMSUNG

- Selected as SAFE* IP Partner in 2018
- Expanding IP cooperation in the fields of memory interface IP

Strengthening external cooperation

HYUNDAI — Affiliates — 42dot
Joint performance of Government autonomous driving project worth KRW 46 billion

bos
IP License Contract

OPENEDGES Technology, Inc.

SK — Affiliates — SAPEON
IP Government project

* SAFE (Samsung Advanced Foundry Ecosystem)

03

2023 Business Performance

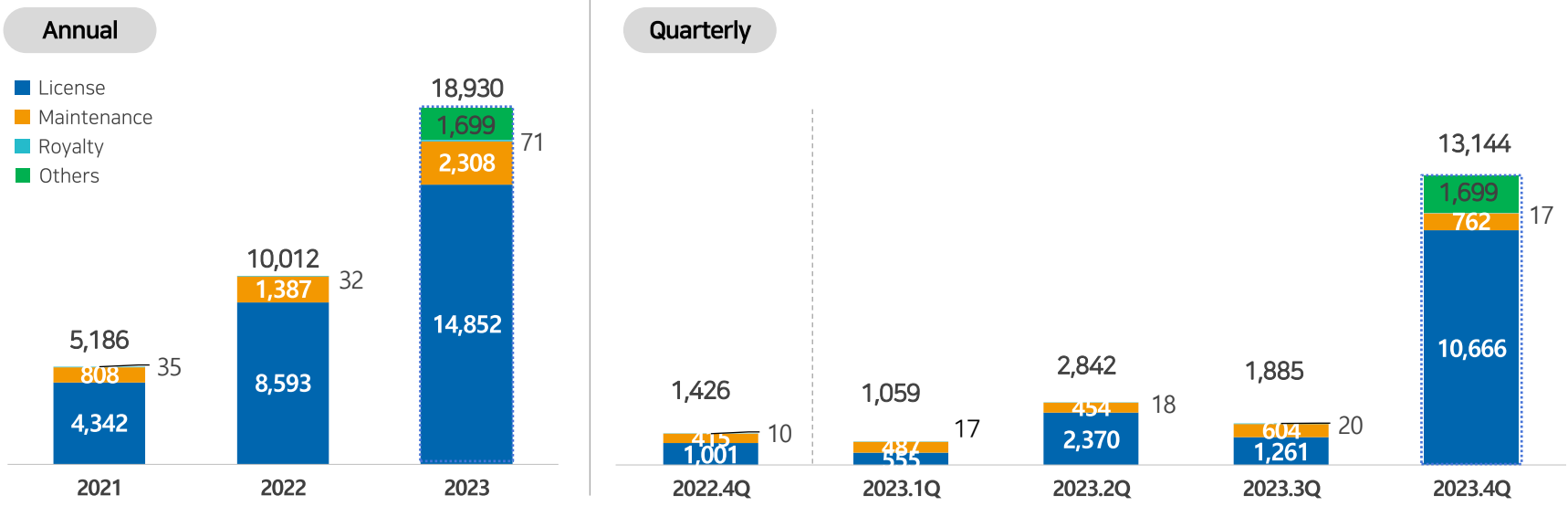
01. Sales
02. Operating Profit(Loss)
03. Contract Status
04. Sales revenue Breakdown

01 | Sales Revenue

Annual sales of KRW 18.9 billion due to growth in license sales (YoY 89%), the 4th quarter also achieved the highest ever quarterly sales (YoY 822%, QoQ 597%). Continued high growth expected in 2024 based on already secured IP product competitiveness

Sales status

(Unit: KRW 1 million)



Sales Analysis

- ✓ **License :** Due to increase in license since 1H of 2023, sales were recognized in earnest from the 4Q23
- ✓ **Maintenance:** Sales are being generated from a total 28 projects
- ✓ **Royalty:** Expected to continue to grow in the future due to increased mass production of chips by customers
- ✓ **Others:** Sales for operational and technical support services for Openedges Square

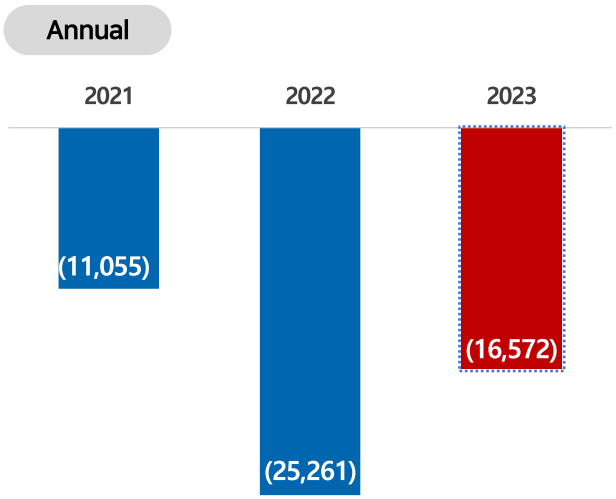
OPENEDGES Technology, Inc.

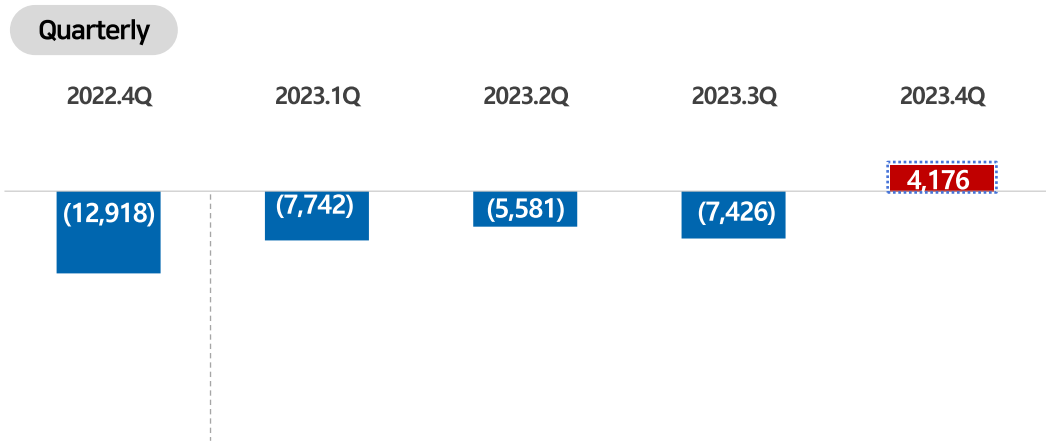
01 | Operating Profit(Loss)

An annual operating loss of KRW 16.6 billion, improved by KRW 8.7 billion YoY
First quarterly surplus in the 4Q23 due to significant growth in sales.
Expecting to improve Profitability significantly in 2024 due to sales growth.

Operating Profit(Loss)

(Unit: KRW 1 million)





Operating Profit Anlaysis

- ✓ Costs in 4Q23 stabilized, sales grew significantly, achieved company's first quarterly surplus.
- ✓ Most of the R&D expenses are for developing new IP, are being managed stably at around KRW 8 to 9 billion per quarter without burdening large one-off costs.
- ✓ Profitability is expected to improve significantly in 2024 due to stable costs and increased sales from IP licensing.

03 | Contract Status

Sales growth slowed in the first half due to the delays in signing license contracts, but expected to grow from the 4Q based on gradually improved market situation

Financial and contract status

(Unit: KRW 1 million)

구분	Quarter				
	23.4Q	23.3Q	QoQ(%)	22.4Q	YoY(%)
Sales	13,144	1,885	597%	1,426	822%
Operating Profit (Loss)	4,176	(7,426)	N/A	(12,918)	N/A
Net Income (Loss)	4,955	(7,310)	N/A	(12,745)	N/A

Contract status

(Unit: case/$M)	License Contract (FY2023)	License Contract (FY2022)	Note
Numbers	12	13	-
Sum of Contract value	$15.5M	$7.5M	2x growth

Performance Analysis and outlook

2023 Results

Significant growth in sales by providing IP tailored to advanced processes & the latest memory standards

- Sales and profitability continue to improve due to ASP increase
  → ASP increase due to provision of advanced process IP such as Samsung 5nm, TSMC 6nm, etc.
- First quarterly surplus and preparing for preemptive market response through continuous IP development
  → Efforts to dominate the market through the development of market leading IPs such as NPU V3.0, LP6 related IPs

2024 Outlook

Expect high sales growth and improved profitability due to IP licensing

- Steady improvements in opportunities to secure contracts from 2H23
- Negotiating with more than 30 customers, including global top-tiers

Expansion of collaboration in technology such as CXL, PIM, & Chiplet

- 3 projects related to CXL ordered in 2023 are in progress
- In 2024, customized projects in the next semiconductor field such as CXL, PIM, and Chiplet are expected to further expand.

04 | Sales revenue Breakdown

Approximately doubles every year, and sales volume by industry also steadily increases

Generates various sales such as automotive and storage devices

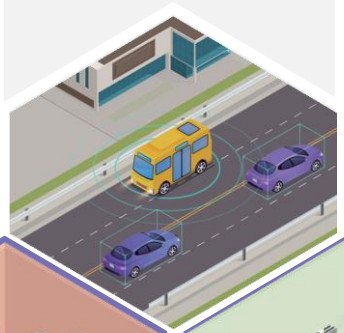
(Unit: KRW)

Server/storage devices

Sales: '22. 2.6bil. → '23. 12.4bil.
(Shares): (26%) → (72%)

Autonomous driving/ In-vehicle face recognition

Sales: '22. 2.7bil → '23. 3.3bil
(Shares): (27%) → (19%)



Sales: '22. 1.9bil → '23. 1.3bil
(Shares): (19%) → (7%)

IoT / Mobile

Sales: '22. 2.1bil → '23. 0.2bil
(Shares): (21%) → (1%)

Display / Drons

Sales: '22. 0.8bil → '23. 0.1bil
(Shares): (8%) → (1%)

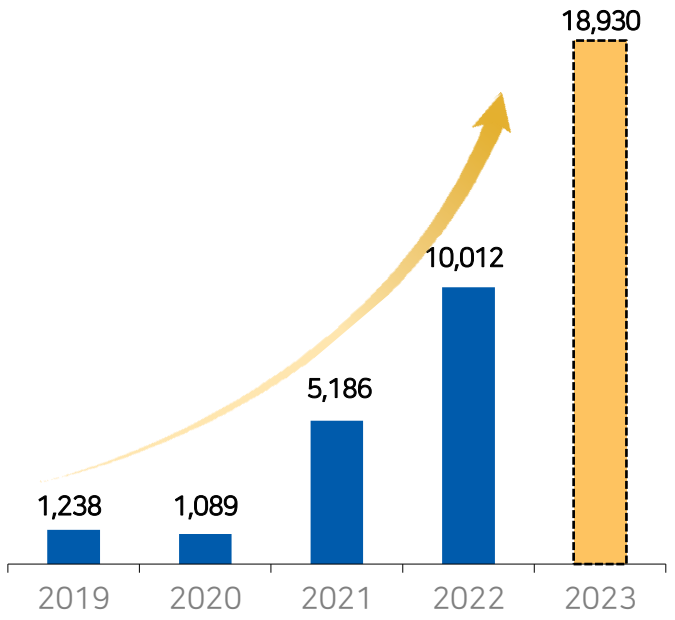
Intelligent security camera

Sales growth begins in earnest after '21

2019~2023 CAGR
+98%

2023 YoY
+89%

(Unit: KRW 1 million)

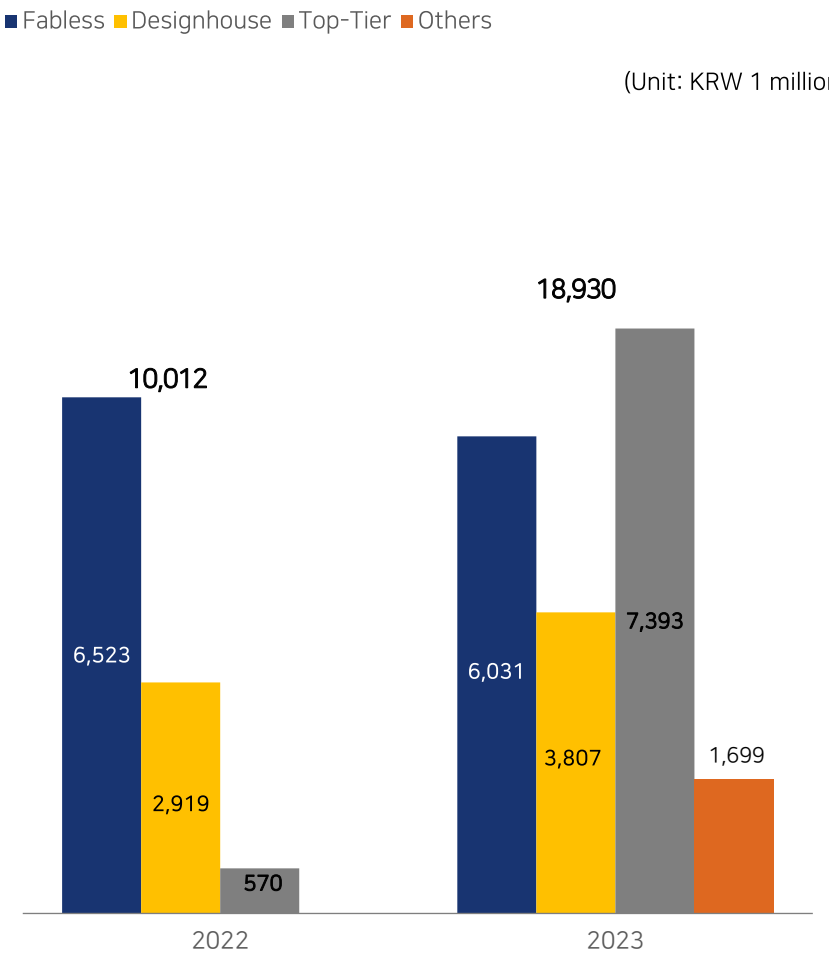


* Excluding other sales (Openedges Square operating and technical support service sales)

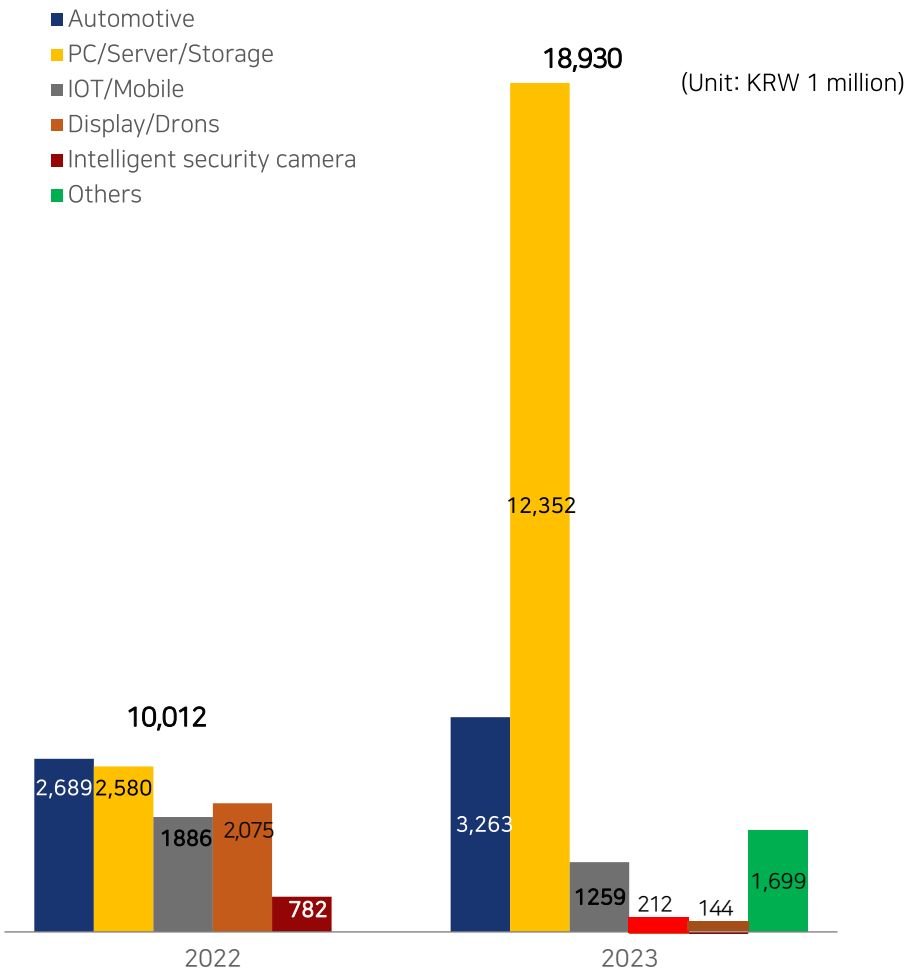
04 | Sales revenue Breakdown

As server needs, such as those related to data centers and CXL, increase, related sales grow significantly.

Sales revenue Breakdown by Customer



Sales revenue Breakdown by application

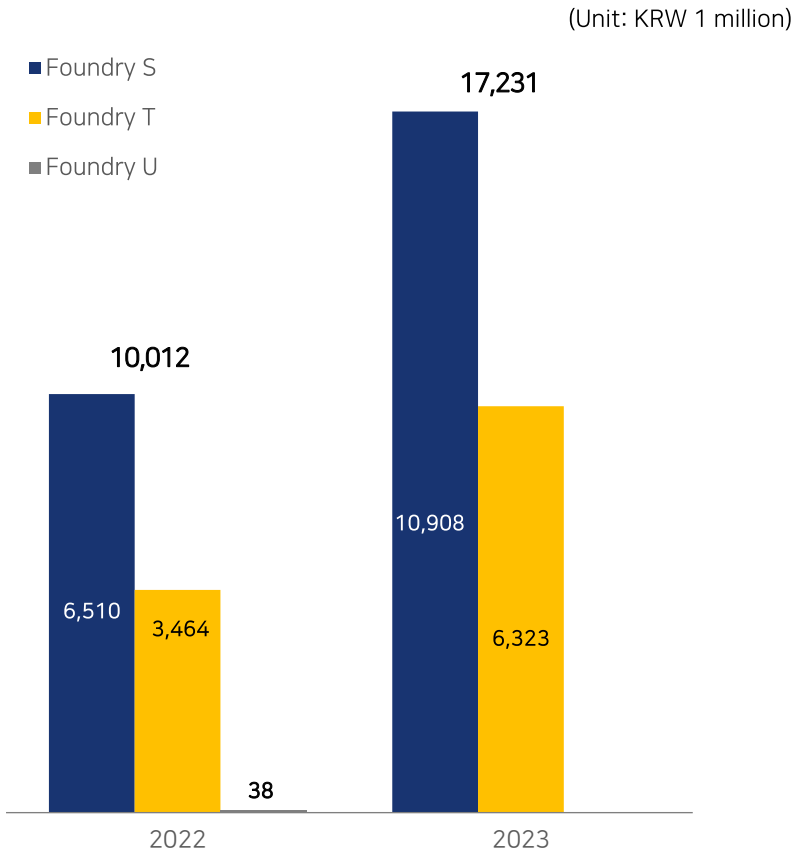


Others: Sales of operational and technical support services for Openedges Square

04 | Sales revenue Breakdown

Sales volume for both of foundry S and T is growing rapidly YoY

Sales by foundry (based on SoC producers equipped with our IP)



Breakdown of Openedges sales revenue by foundry

☐ Continued growth in sales volume of the two major foundries

Foundry S: Growth continues due to increased sales of lp5x related PHY IP

Foundry T: Rapid increase in related IP sales even before joining IP Alliance

* After joining the IP Alliance of T, orders from T's customers are expected to surge

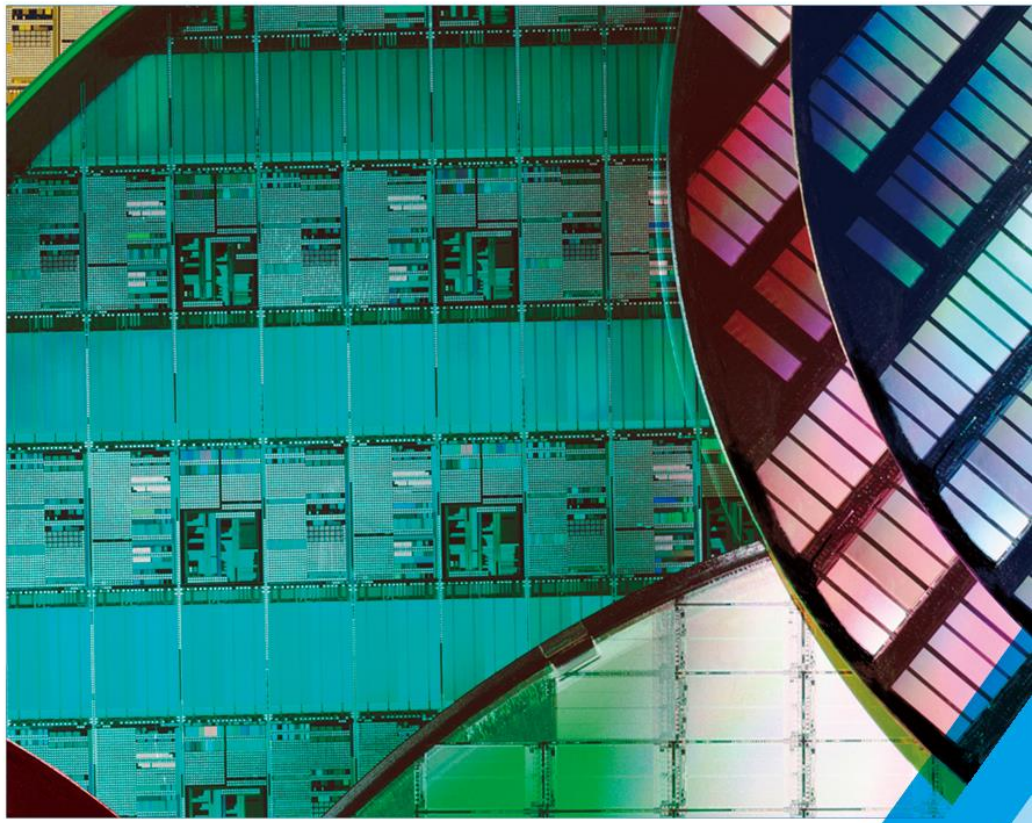
'21~'23 Openedges sales revenue by Foundries

	'21	'22	'23	YoY	CAGR ('21~'23)
S	3,182	6,510	10,908	67.6%	85%
(%)	(61%)	(65%)	(63%)		
T	1,661	3,464	6,323	82.5%	95%
(%)	(32%)	(35%)	(37%)		
U	343	38	-	-	
Total	**5,186**	**10,012**	**17,231**	**-**	**-**

* Excluding other sales (Openedges Square operating and technical support service sales)

04

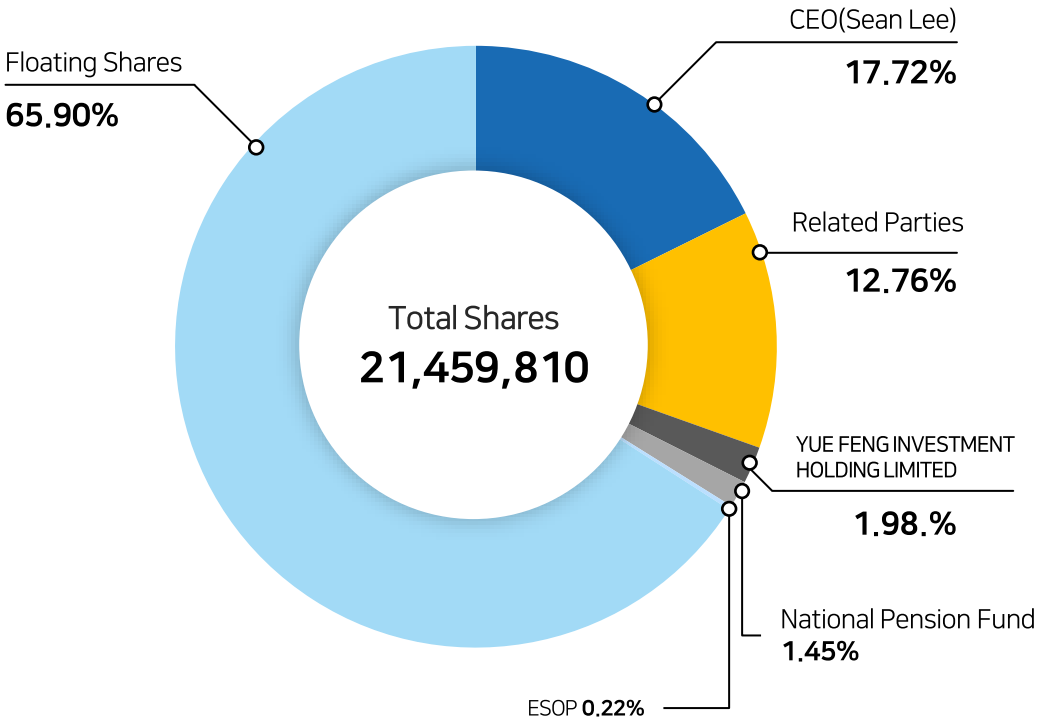
Appendix



01 | Shareholders

Sean Lee(including related parties) owns a stake of 30.45%, securing management rights through stable ownership.

Shareholders



Name	Type	# of shares	%
CEO(Sean Lee)	Common	3,796,314	17.72%
Related Parties	Common	2,738,293	12.76%
YUE FENG INVESTMENT HOLDING LIMITED	Common	425,000	1.98%
National Pension Fund	Common	311,095	1.45%
ESOP	Common	47,999	0.22%
Floating Shares	Common	14,141,109	65.90%
Total		**21,459,810**	**100.00%**

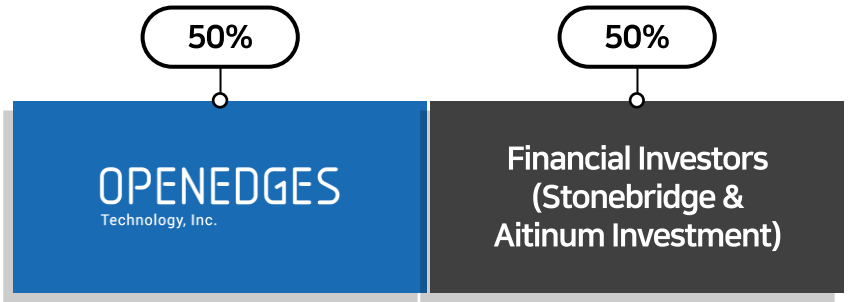
※ As of Dec. 31, 2023

02 | Openedges Square - Summary

Company Profile

Name	OPENEDGES Square
CEO	Sean Lee
Establishment	August 2023
Capital	36 bil.(Openedges l8 bil. Investment in kind) (2 financial investors: 18 bil. Investment in cash)
Employees	7 people (as of November 1, 2023)
Workplace	Headquarters: 10th floor, Hyeonjuk Building, 114 Yeoksam-ro, Gangnam-gu, Seoul
Key points	Openedges HQ holds a call option for 35% of the financial investor's shares.

Shareholders



Business Status

OPENEDGES
Technology, Inc.

Tarteting fast commercialization and make stable growth through the synergy with the current Openedges' IP product portfolio

"OPENEDGES Square"

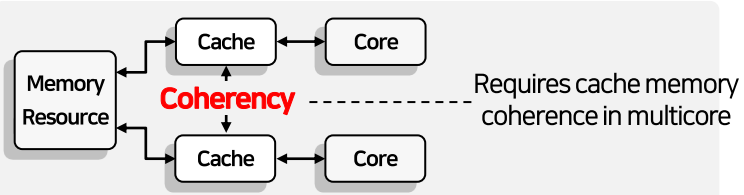
Multi-core Processor based IP development	Processor's computation burden within AI semiconductors → Target to develop core functional blocks to reduce the burden *Cache-Coherent NoC
IP Sales platform business	To change the current resource-consuming SoC design paradigm, → Target to develop and supply IP Sales platform

02 | Openedges Square - Main business areas

Multi-core processor-based IP development business

Cache-Coherent NoC(CC NoC) Necessity

As semiconductor design becomes more complex, data transmission inconsistencies between each processor cause calculation errors.



A core functional block within the AI semiconductor responsible for maintaining the same cache data between multi-cores.

IP development and success factors | IP development to prevent calculation errors

OPENEDGES Technology, Inc.

Technology success DNA

- 4 Core IPs in AI chip market
- Technological correlation with NCC-NoC from Openedges

Market entry through existing sales channels

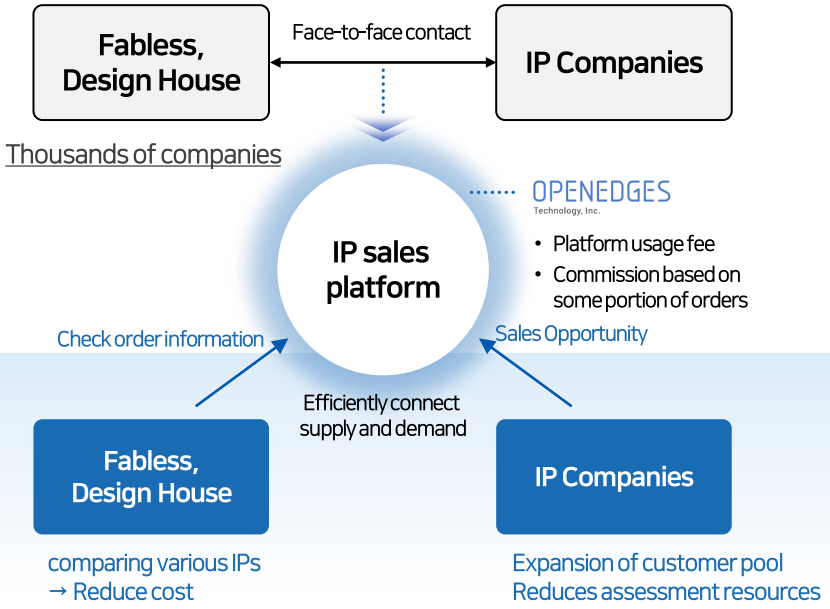
- Sales personnel & 9 overseas sales agents
- Total solution can be supplied by linking with existing IP

Present

Future

IP sales platform business

The need for an IP sales platform due to the exhaustive IP licensing process



Success factors for web-based SoC design platform

Memory System IP developed by Open edges can be actively utilized	Openedges enables effective market entry targeting existing customers	Efficient operation possible through shared service agreement with Openedges

03 | Financial Statements Summary

Summary of Financial Statements

(Unit: KRW 1 million)

	2023	2022	2021	2020
Current Assets	29,903	44,304	29,020	6,216
Non-current Assets	14,447	9,552	7,077	4,075
Total Assets	**44,350**	**53,855**	**36,097**	**10,291**
Current Liabilities	19,704	18,318	9,171	5,477
Non-current Liabilities	4,762	3,288	6,374	31,551
Total Liabilities	**24,466**	**21,606**	**15,545**	**37,028**
Capital	2,146	2,116	1,653	15
Capital Surplus	98,259	96,376	58,927	-
Other Capital	3,578	2,026	3,007	1,697
Retained earnings	-84,099	-68,269	-43,035	-28,449
Total Equity	**19,884**	**32,249**	**20,553**	**-26,737**

※ Based on consolidated financial statements

Summary of Income Statements

(Unit: KRW 1 million)

	2023	2022	Change	Change(%)
Sales	**18,930**	**10,012**	8,918	89.1
Sales Management Expenses	35,502	35,273	229	0.6
Operating Profits	**-16,572**	**-25,261**	8,689	*N/A*
Financial Profits	1,502	1,409	93	6.6
Financial Costs	1,248	1,067	181	17.0
Other Profits	789	476	313	65.8
Other Costs	26	402	-377	-93.6
Net Profit before Corporate Tax Costs	**-15,556**	**-24,846**	9,291	*N/A*
Corporate Tax Costs	-12	380	-393	*N/A*
Current Net Income	**-15,543**	**-25,227**	9,683	*N/A*

※ Based on consolidated financial statements